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May 2016

FGY160T65SPD_F085 650V, 160A Field Stop Trench IGBT With Soft Fast Recovery Diode

Features

- · Automotive Qualified
- Very low saturation voltage : $V_{CE(sat)} = 1.6 \text{ V(Typ.)}$ @ $I_{C} =$ 160 A
- Maximum junction temperature : T_J = 175 °C
- · Positive temperature Co-efficient
- · Tight parameter distribution
- · High input impedance
- 100% of the parts are dynamically tested
- Short circuit ruggedness > 6 μs @ 25 °C
- · Copacked with soft, fast recovery Extremefast diode

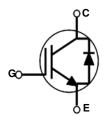
Benefits

- Very Low conduction and switching losses for a high efficiency operation in various applications
- Rugged transient reliability
- Outstanding parallel operation performance with balance cur-
- Low EMI

Applications

- Traction inverter for HEV/EV
- Auxiliary DC/AC converter
- · Motor drives
- Other power-train applications requiring high power switch





Absolute Maximum Ratings

Symbol	Description		Ratings	Units
V _{CES}	Collector to Emitter Voltage		650	V
V _{GES}	Gate to Emitter Voltage		± 20	V
Ic	Collector Current (Note1)	@ T _C = 25 °C	240	Α
l iC	Collector Current	@ T _C = 100 °C	220	Α
I _{Nominal}	Nominal Current		160	Α
I _{CM}	Pulsed Collector Current		480	Α
I _F	Diode Forward Current (Note1)	@ T _C = 25 °C	240	Α
	Diode Forward Current	@ T _C = 100 °C	188	Α
D	Maximum Power Dissipation	@ T _C = 25 °C	882	W
P_{D}	Maximum Power Dissipation	@ T _C = 100 °C	441	W
SCWT	Short Circuit Withstand Time	@ T _C = 25 °C	6	μS
dV/dt	Voltage Transient Ruggedness (Note2)		10	V/ns
TJ	Operating Junction Temperature		-55 to +175	°C
T _{stg}	Storage Temperature Range		-55 to +175	°C
T _L	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C

Notes:
1: Limited by bondwire

2: $V_{CC} = 400 \text{ V}$, $V_{GE} = 15 \text{ V}$, $I_{CE} = 480 \text{ A}$, Inductive Load

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	-	0.17	°C/W
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	-	0.32	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	-	40	°C/W

Package Marking and Ordering Information

Device Marking Device		Package	Packing Type	Qty per Tube	
FGY160T65SPD	FGY160T65SPD_F085	TP-247	Tube	30ea	

For Fairchild's definition of "green" Eco Status, please visit: http://www.fairchildsemi.com/company/green/rohs_green.html.

Electrical Characteristics of the IGBT $T_{J} = 25 \, ^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Charac	eteristics					
BV _{CES}	Collector to Emitter Breakdown Voltage	$V_{GE} = 0V, I_C = 1mA$	650	-	-	V
$\Delta BV_CES \ \Delta T_J$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0V$, $I_C = 1mA$	-	0.6	-	V/°C
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$	-	-	40	μА
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$	-	-	± 250	nA
On Charac	teristics					
V _{GE(th)}	G-E Threshold Voltage	I _C = 160mA, V _{CE} = V _{GE}	4.3	5.3	6.3	V
. ,		I _C = 160A, V _{GE} = 15V	-	1.6	2.05	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	I _C = 160A, V _{GE} = 15V, T _J = 175 °C	-	2.15	-	٧
Dynamic C	Characteristics					
C _{ies}	Input Capacitance		-	6710	-	pF
C _{oes}	Output Capacitance	$V_{CE} = 30V, V_{GE} = 0V,$	-	450	-	pF
C _{res}	Reverse Transfer Capacitance	f = 1MHz	-	55	-	pF
R _G	Internal Gate Resistance	f = 1MHz	-	3	-	Ω
Switching	Characteristics				I.	
T _{d(on)}	Turn-On Delay Time		-	53	-	ns
T _r	Rise Time		-	197	-	ns
T _{d(off)}	Turn-Off Delay Time	V _{CC} = 400V, I _C = 160A,	-	98	-	ns
T _f	Fall Time	$R_G = 5\Omega$, $V_{GE} = 15V$,	-	141	-	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _J = 25 °C	-	12.4	-	mJ
E _{off}	Turn-Off Switching Loss		-	5.7	-	mJ
E _{ts}	Total Switching Loss		-	18.1	-	mJ
T _{d(on)}	Turn-On Delay Time		-	52	-	ns
T _r	Rise Time	V_{CC} = 400V, I_{C} = 160A, R_{G} = 5 Ω , V_{GE} = 15V, Inductive Load, T_{J} = 175 $^{\circ}$ C	-	236	-	ns
T _{d(off)}	Turn-Off Delay Time		-	104	-	ns
T _f	Fall Time		-	204	-	ns
E _{on}	Turn-On Switching Loss		-	21	-	mJ
E _{off}	Turn-Off Switching Loss		-	8.5	-	mJ
E _{ts}	Total Switching Loss		-	29.5	-	mJ

Electrical Characteristics of the IGBT (Continued)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max	Units
Q_g	Total Gate Charge	V _{CE} = 400V, I _C = 160A, V _{GE} = 15V	-	163	245	nC
Q _{ge}	Gate to Emitter Charge		-	50	-	nC
Q _{gc}	Gate to Collector Charge		-	49	-	nC

Electrical Characteristics of the Diode $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max	Units
V _{FM}	Diode Forward Voltage	I _F = 160A	$T_J = 25$ °C	-	1.4	1.7	V
			$T_J = 175$ °C	-	1.35	-	
F Deverse Bessyam Francis	Payaraa Pagayary Engray	$V_{CE} = 400V$, $I_F = 160A$, $dI_F/dt = 1000A/\mu s$	$T_J = 25$ °C	-	598	-	1
E _{rec}	Reverse Recovery Energy		T _J = 175 °C	-	4000	-	- μJ
Т	T _{rr} Diode Reverse Recovery Time		T _J = 25 °C	-	132	-	ns
·rr			T _J = 175 °C	-	245	-	110
Q _{rr}	Q _{rr} Diode Reverse Recovery Charge		T _J = 25 °C	-	3.3	-	иC
∠ II	Disas rieverse riesevery enarge		T _J = 175 °C	-	12.5	1	μο

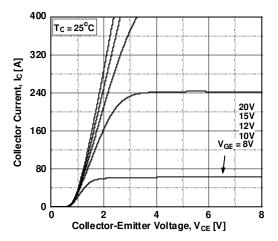


Figure 1. Typical Output Characteristics

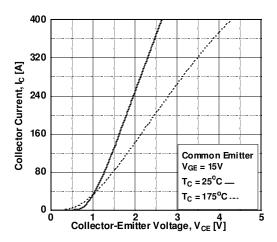


Figure 3. Typical SaturationVoltage

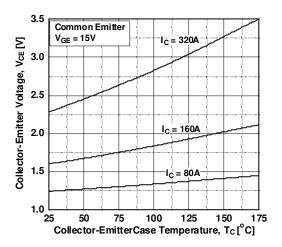


Figure 5. Saturation Voltage vs. Case

Temperature at Varient Current Level

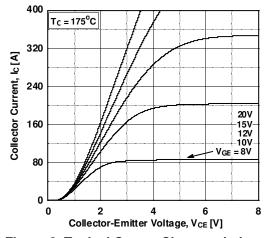


Figure 2. Typical Output Characteristics

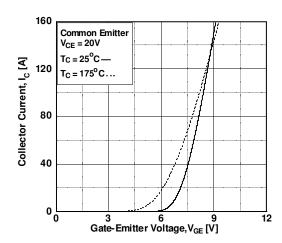


Figure 4. Transfer Charactersistics

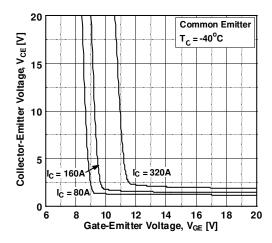


Figure 6. Saturation Voltage vs. VGE

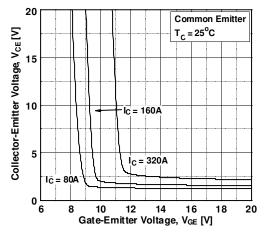


Figure 7. Saturation Voltage vs. VGE

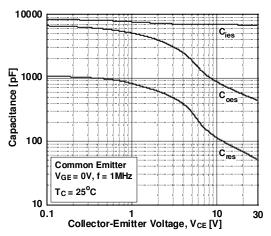


Figure 9. Capacitance Charateristics

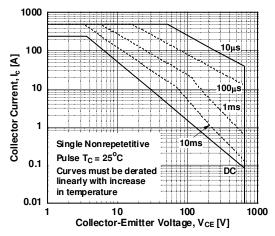


Figure 11. SOA Charateristics

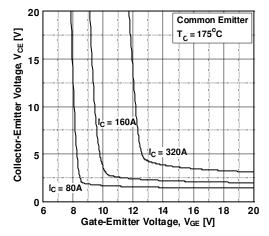


Figure 8. Saturation Voltage vs. VGE

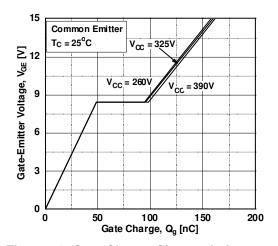


Figure 10. Gate Charge Charateristics

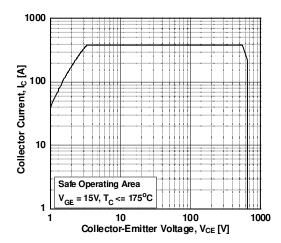


Figure 12. Turn off Switching SOA Charateristics

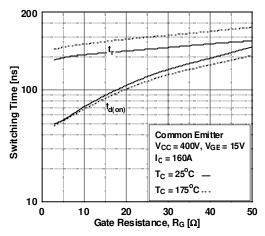


Figure 13. Turn-on Charaterizatics vs. Gate

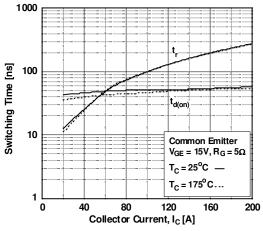


Figure 15. Turn-on Charaterizatics vs.

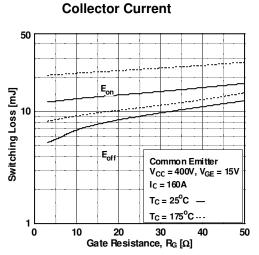


Figure 17. Switching Loss vs. Gate Resistance

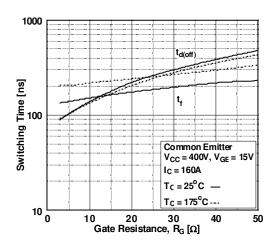


Figure 14. Turn-off Charaterizatics vs. Gate

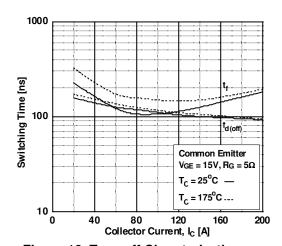


Figure 16. Turn-off Charaterizatics vs.

Collector Current

Common Emitter $V_{GE} = 15V, R_G = 5\Omega$ $T_C = 25^{\circ}C$... $T_C = 175^{\circ}C$... $T_C = 175^$

Figure 18. Switching Loss vs. Collector Current

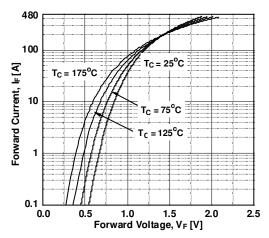


Figure 19. Forward Charateristics

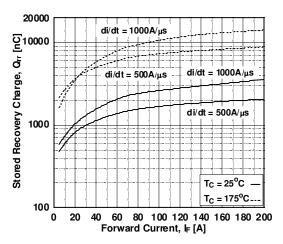


Figure 21. Stored Charge

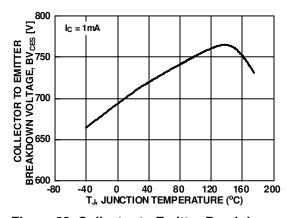


Figure 23. Collector to Emitter Breakdown
Voltage vs. Junction Temperature

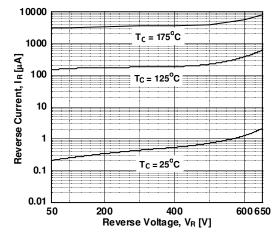


Figure 20. Reverse Current

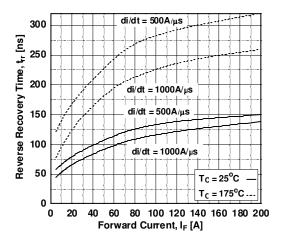


Figure 22. Reverse Recovery Time

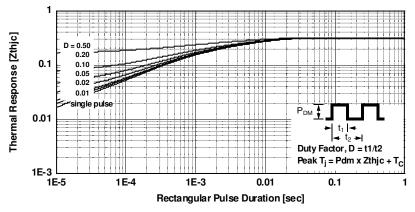


Figure 24. Transient Termal Impedance of Diode

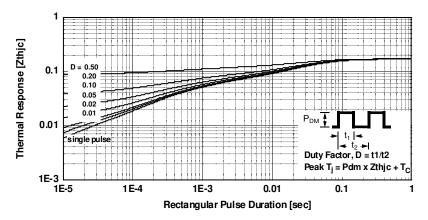
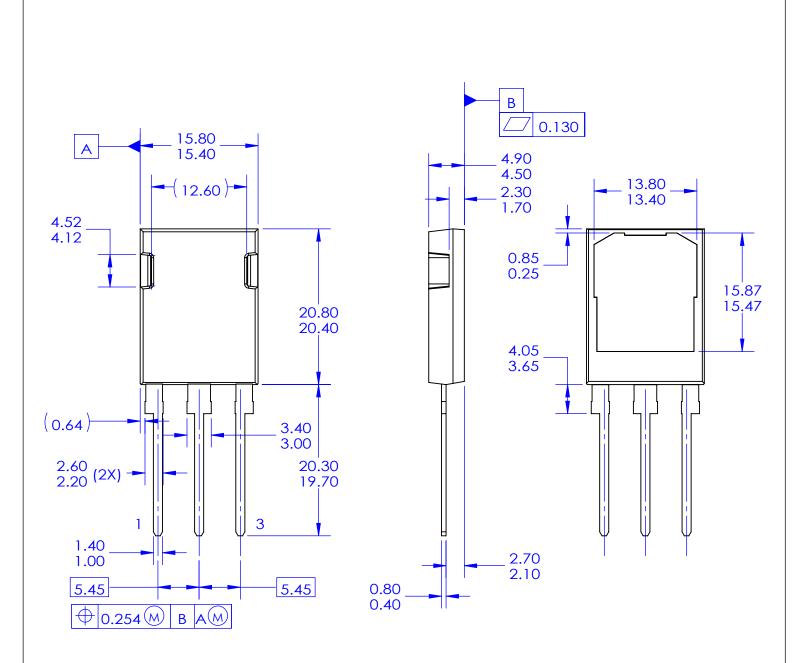


Figure 25. Transient Termal Impedance of IGBT



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